

Datasheet revision 1.0

www.chipquik.com

Chip Removal Alloy (16 feet, 0.8mm THIN Diameter) for SMD/SMT (30-6.5" sticks)

Product Highlights Easily remove SMD parts with **Chip Quik**® removal alloy Reduce heat and reduce damage to circuit boards and SMD parts during removal Comes with SMDLT flux

Specifications	
Alloy:	Chip
Alloy Melting Point:	58°Ċ
Thickness:	0.8mi
Flux:	SMD
Flux Type:	No-C
Flux Classification:	REL0
Flux Activation Temperature:	100°0

hip Quik® Alloy Leaded 30-6.5in. Thin Sticks 8°C (136°F) .8mm (0.031") MDLT 2cc/2g Squeeze Tube o-Clean EL0 00°C (212°F)



Chip Quik® Instructions		
	1	Apply Chip Quik flux to all leads of SMD with syringe or flux applicator.
	2	Melt Chip Quik low temperature alloy uniformly on all pins of SMD. Maintain alloy in molten state long enough for complete reflow.
3	3	Lift chip from board with dental pick or vacuum pen.
	4	Thoroughly clean site with swab dipped in flux while applying heat. Clean thoroughly with alcohol pad.

SMD Removal

(With solder iron or warm air bath)

- Apply flux to all leads.
- Melt CHIP QUIK® uniformly on all pins.
- Maintain alloy in molten state long enough to release chip.
- Lift chip from board with dental pick or vacuum pen.

CLEAN UP

- While molten, use cotton swab and flux to move excess to an unused section of board.
- While applying heat, polish each pad with a swab and flux until thoroughly clean.
- At room temperature, clean residue with alcohol pad.
- You are now ready to install the new chip.

5 ft of thin sticks of Chip Quik® material, removes 1250 to 1500 SMD pins.

Conforms to the following Industry Standards: J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): RoHS 3 Directive (EU) 2015/863:

Yes No